

ISO/~~TR~~DTR 9839

~~2023-09~~

ISO/TC 22/SC 32

Secretariat: ~~AFNOR~~ IISC

Date: 2023-05-10

## Road vehicles — Application of predictive maintenance to hardware with ISO 26262-5

Véhicules routiers — Application de ~~l'entretien~~ la maintenance prédictive au matériel ~~avec ISO~~ à l'aide de l'ISO 26262-5

iTeh STANDARD PREVIEW  
(standards.iteh.ai)

FDIS stage DTR 9839

<https://standards.iteh.ai/catalog/standards/sist/6bd5697e-37fa-42b1-aa4f-f22a959c9a65/iso-dtr-9839>

© ISO 2023

All rights reserved. Unless otherwise specified, or required in the context of its implementation, no part of this publication may be reproduced or utilized otherwise in any form or by any means, electronic or mechanical, including photocopying, or posting on the internet or an intranet, without prior written permission. Permission can be requested from either ISO at the address below or ISO's member body in the country of the requester.

ISO copyright office  
CP 401 • Ch. de Blandonnet 8  
CH-1214 Vernier, Geneva  
Phone: + 41 22 749 01 11

Fax: +41 22 749 09 47

Email: [copyright@iso.org](mailto:copyright@iso.org)  
Website: [www.iso.org](http://www.iso.org)

Published in Switzerland

## iTeh STANDARD PREVIEW (standards.iteh.ai)

[ISO/DTR 9839](https://standards.iteh.ai/catalog/standards/sist/6bd5697e-37fa-42bc-aa4f-f22a959c9a65/iso-dtr-9839)

<https://standards.iteh.ai/catalog/standards/sist/6bd5697e-37fa-42bc-aa4f-f22a959c9a65/iso-dtr-9839>

**Contents**

Foreword ..... v

Introduction ..... vi

1 Scope ..... 1

2 Normative references ..... 1

3 Terms and definitions ..... 1

4 Abbreviated terms ..... 2

5 Literature survey of degrading faults ..... 5

5.1 General ..... 5

5.2 Degrading faults in industry standards ..... 5

5.2.1 JEDEC JEP122H<sup>[4]</sup> ..... 5

5.3 Degrading faults in technical publications ..... 6

5.3.1 Advanced CMOS Reliability Update: Sub 20 nm FinFET Assessment<sup>[5]</sup> ..... 6

5.3.2 Circuit-Based Reliability Consideration in FinFET Technology<sup>[6]</sup> ..... 7

5.3.3 Intermittent Faults and Effects on Reliability of Integrated Circuits<sup>[7]</sup> ..... 7

6 Literature survey on predictive maintenance ..... 8

6.1 General ..... 8

6.2 Predictive maintenance in industry standards ..... 8

6.2.1 IEC 61508<sup>[9]</sup> ..... 8

6.2.2 IEEE 1856<sup>[3]</sup> ..... 8

6.3 Predictive maintenance in technical publications ..... 9

6.3.1 A Survey of Online Failure Prediction Methods<sup>[10]</sup> ..... 9

6.3.2 An Odometer for CPUs<sup>[11]</sup> ..... 9

6.3.3 Circuit Failure Prediction for Robust System Design in Scaled CMOS<sup>[12]</sup> ..... 10

6.3.4 A Circuit Failure Prediction Mechanism (DART) for High Field Reliability<sup>[13]</sup> ..... 10

6.3.5 Predicting Remediations for Hardware Failures in Large-Scale Datacenters<sup>[14]</sup> ..... 10

6.3.6 Improving Analog Functional Safety Using Data-Driven Anomaly Detection<sup>[15]</sup> ..... 10

7 Degrading faults and the ISO 26262 series ..... 10

7.1 Understanding the lifecycle of degrading faults ..... 10

7.2 Classification of degrading faults ..... 14

7.3 Quantifying degrading fault base failure rate ..... 15

7.3.1 Industry standards and models ..... 15

7.3.2 Field data ..... 15

7.3.3 Expert judgement ..... 15

8 Applying predictive maintenance ..... 15

8.1	Diagnostic coverage (DC) evaluation for predictive mechanisms.....	15
8.2	Considering random hardware metrics .....	16
8.2.1	Impacting the SPFM and LFM .....	16
8.2.2	Application as a dedicated measure.....	16
8.3	Considering RUL prediction .....	17
Annex A (informative)	An approach to handling degrading faults.....	18
Bibliography	.....	20

iTeh STANDARD PREVIEW  
(standards.iteh.ai)

ISO/DTR 9839

<https://standards.iteh.ai/catalog/standards/sist/6bd5697e-37fa-42bc-aa4f-f22a959c9a65/iso-dtr-9839>

## Foreword

ISO (the International Organization for Standardization) is a worldwide federation of national standards bodies (ISO member bodies). The work of preparing International Standards is normally carried out through ISO technical committees. Each member body interested in a subject for which a technical committee has been established has the right to be represented on that committee. International organizations, governmental and non-governmental, in liaison with ISO, also take part in the work. ISO collaborates closely with the International Electrotechnical Commission (IEC) on all matters of electrotechnical standardization.

The procedures used to develop this document and those intended for its further maintenance are described in the ISO/IEC Directives, Part 1. In particular, the different approval criteria needed for the different types of ISO documents should be noted. This document was drafted in accordance with the editorial rules of the ISO/IEC Directives, Part 2 (see [www.iso.org/directives](http://www.iso.org/directives)).

~~Attention is drawn to the possibility that some of the elements of this document may be the subject of a patent right. ISO takes no position concerning the evidence, validity or applicability of any claimed patent rights in respect thereof. As of the date of publication of this document, ISO had not received notice of (a) patent(s) which may be required to implement this document. However, implementers are cautioned that this may not represent the latest information, which may be obtained from the patent database available at [www.iso.org/patents](http://www.iso.org/patents). ISO shall not be held responsible for identifying any or all such patent rights. Details of any patent rights identified during the development of the document will be in the Introduction and/or on the ISO list of patent declarations received (see -).~~

Any trade name used in this document is information given for the convenience of users and does not constitute an endorsement.

For an explanation of the voluntary nature of standards, the meaning of ISO specific terms and expressions related to conformity assessment, as well as information about ISO's adherence to the World Trade Organization (WTO) principles in the Technical Barriers to Trade (TBT), see [www.iso.org/iso/foreword.html](http://www.iso.org/iso/foreword.html).

This document was prepared by Technical Committee ISO/TC 22, Road ~~Vehicles~~ vehicles, Subcommittee SC 32, ~~Electrical and electronic components and general system aspects~~.

Any feedback or questions on this document should be directed to the user's national standards body. A complete listing of these bodies can be found at [www.iso.org/members.html](http://www.iso.org/members.html).

## Introduction

Hardware elements wear out or degrade with time and usage. The presence of certain faults can cause the rate of degradation to increase. If the rate of degradation exceeds critical thresholds, then a hardware element can fail during its normal expected lifespan. Addressing fault behaviours which change over time is difficult. Functional safety standards such as [the ISO 26262 series](#) have traditionally addressed degrading faults with avoidance measures and simplified assumptions of static behaviours.

Understanding of degrading faults is improving over time. Many industries are taking proactive steps to control degrading faults using predictive maintenance. Predictive maintenance can detect degrading faults and predict remaining useful life. Safety mechanisms based on predictive maintenance are not explicitly discussed in [the ISO 26262:2018 series](#).

This document provides a survey of current state of the art for degrading faults and predictive maintenance techniques. Approaches are presented to consider degrading faults and predictive maintenance techniques in an ISO 26262 safety argument. Much of the content is focused on semiconductors, but the concepts can be applied to other hardware elements.

iTeh STANDARD PREVIEW  
(standards.iteh.ai)

[ISO/DTR 9839](#)

<https://standards.iteh.ai/catalog/standards/sist/6bd5697e-37fa-42bc-aa4f-f22a959c9a65/iso-dtr-9839>

# Road vehicles — Application of predictive maintenance to hardware with ISO 26262-5

## 1 Scope

This document is intended to be applied to the usage of predictive maintenance methods for the detection of degrading faults in safety related E/E hardware elements. It applies to hardware elements developed for compliance with the ISO 26262<sup>[1]</sup> series in which degrading faults are shown to be relevant due to, for instance, the technology used.

Specific technical implementations of predictive maintenance solutions are not in scope of this document.

## 2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

ISO 26262-1:2018, *Road vehicles — Functional Safety — Part 1: Vocabulary*

~~ISO 26262-5:2018, *Road vehicles — Functional Safety — Part 5: Product development at the hardware level*~~

## 3 Terms and definitions

For the purposes of this document, the terms and definitions given in ISO 26262-1:2018 and the following apply.

ISO and IEC maintain terminological terminology databases for use in standardization at the following addresses:

— ISO Online browsing platform: available at <https://www.iso.org/obp>

— IEC Electropedia: available at <https://www.electropedia.org/>

### 3.1

#### degrading fault

fault whose characteristics are not constant and degrade over time, that can result in an error or failure when stimulated after degradation exceeds a critical threshold

Note 1 to entry: Permanent and intermittent faults can first manifest as degrading faults. Transient faults do not manifest as degrading faults.

Note 2 to entry: Degrading faults do not create errors or failures until degradation exceeds critical thresholds. The capability to generate an error or failure is related to the current state of degradation.

Note 3 to entry: Degrading faults exhibit abnormal conditions which can cause an error or failure over time. Normal degradation does not exhibit abnormal conditions which are necessary to be classified as a fault. Normal degradation can result in a loss of functionality after expected lifespan has elapsed but cannot be considered a fault as it is not abnormal.

### 3.2

#### degrading fault detection time interval

~~{DFDTI}~~

timespan from the occurrence of a *degrading fault* (3.1) to its detection

## ISO/DTR 9839:(E)

### 3.3

#### degrading fault handling time interval

~~{DFHTI}~~

sum of the *degrading fault detection time interval* [\(3.2\)](#) and the *degrading fault reaction time interval* [\(3.4\)](#).

Note 1 to entry: The degrading fault handling time interval is a property of a *predictive maintenance* [\(3.5\)](#) related safety mechanism.

Note 2 to entry: The degrading fault handling time interval is considered in addition to the fault handling time interval. See [Figure 4](#).

Note 3 to entry: The timespan from occurrence of a *degrading fault* [\(3.1\)](#) until it has the capability to generate an error or failure is the maximum degrading fault handling time interval that can be specified for a predictive maintenance related safety mechanism to support the functional safety concept.

Note 4 to entry: A *degrading fault* [\(3.1\)](#) is covered in a timely manner by the corresponding safety mechanism if there is detection and reaction within the degrading fault handling time interval.

### 3.4

#### degrading fault reaction time interval

~~{DFRTI}~~

timespan from the detection of a *degrading fault* [\(3.1\)](#) to reaching a safe state or reaching emergency operation

### 3.5

#### predictive maintenance

techniques that are used to detect *degrading faults* [\(3.1\)](#), predict *remaining useful life* [\(3.6\)](#), and react appropriately

Note 1 to entry: Approaches include the use of data driven methods such as machine learning applied locally or on a remote system. Guidance for developing safety related ML systems can be found in ISO/IEC TR 5469 and ISO PAS [aa4f-f22a959c9a65/iso-8800-1](#).

Note 2 to entry: Prediction of *remaining useful life* [\(3.6\)](#) can be used to replace a faulty element before it can cause an error or failure.

### 3.6

#### remaining useful life

~~{RUL}~~

length of time from the present time to the estimated time that the item or element is expected to no longer perform its intended function within desired specifications

[SOURCE: IEEE Std 1856-2017, modified for compliance to ISO directives]

Note 1 to entry: RUL can be estimated using *predictive maintenance* [\(3.5\)](#) or with other approaches.

Note 2 to entry: RUL can be estimated for expected degradation or degradation in the presence of a fault.

[SOURCE: IEEE 1856-2017<sup>[3]</sup>, modified for compliance to ISO directives]

## 5.4 Abbreviated terms

ADAS ——— Advanced Driver Assistance System

ADS ——— Automated Driving System



AI	Artificial Intelligence
BEoL	Back End of Line (sometimes BEOL)
BFR	Base Failure Rate
BIST	Built In Self Test
BLM	Barrier Layer Material
CHC	Channel Hot Carrier
COTS	Commercial Off The Shelf
DC	Diagnostic Coverage
DFDTI	Degrading Fault Detection Time Interval
DFHTI	Degrading Fault Handling Time Interval
DFRTI	Degrading Fault Reaction Time Interval
DRAM	Dynamic Random Access Memory
EM	Electromigration
ESD	Electrostatic Discharge
FEoL	Front End of Line (sometimes FEOL)
FET	Field Effect Transistor
FDTI	Fault Detection Time Interval
FHTI	Fault Handling Time Interval
FTTI	Fault Tolerant Time Interval
HCI	Hot Carrier Injection
ILD	Inter Layer Dielectric
LFM	Latent Fault Metric
ML	Machine Learning
MoL	Middle of Line (sometimes MOL)
MEoL	Middle End of Line (sometimes MEOL)
MPFDTI	Multiple Point Fault Detection Time Interval
NBTI	Negative Bias Temperature Instability
NVM	Non Volatile Memory
PCM	Phase Change Memory

**ISO/DTR 9839:(E)**

**PHM** ——— **Prognostics and Health Management**

**QMS** ——— **Quality Management System**

**RUL** ——— **Remaining Useful Life**

**SBD** ——— **Soft Breakdown**

**SHE** ——— **Self Heating Effect**

**SILC** ——— **Stress Induced Leakage Current**

**SM** ——— **Stress Migration**

**SoC** ——— **System on Chip**

**SPFM** ——— **Single Point Fault Metric**

**TDDB** ——— **Time Dependent Dielectric Breakdown**

**TDJD** ——— **Time Dependent Junction Degradation**

**TID** ——— **Total Ionizing Dose**

**ADAS** ——— **Advanced Driver Assistance System**

**ADS** ——— **Automated Driving System**

**AI** ——— **Artificial Intelligence**

**BEoL** ——— **Back End of Line (sometimes BEOL)**

**BFR** ——— **Base Failure Rate**

**BLM** ——— **Barrier Layer Material**

**CHC** ——— **Channel Hot Carrier**

**COTS** ——— **Commercial Off The Shelf**

**DC** ——— **Diagnostic Coverage**

**DFDTI** ——— **Degrading Fault Detection Time Interval**

**DFHTI** ——— **Degrading Fault Handling Time Interval**

**DFRTI** ——— **Degrading Fault Reaction Time Interval**

**DRAM** ——— **Dynamic Random Access Memory**

**EM** ——— **Electromigration**

**ESD** ——— **Electrostatic Discharge**

**FEoL** ——— **Front End of Line (sometimes FEOL)**

**FET** ——— **Field Effect Transistor**

**FDTI** ——— **Fault Detection Time Interval**

**FHTI** ——— **Fault Handling Time Interval**

**FTTI** ——— **Fault Tolerant Time Interval**

**HCI** ——— **Hot Carrier Injection**

ITEH STANDARD PREVIEW  
(standards.iteh.ai)

ISO/DTR 9839

<https://standards.iteh.ai/catalog/standards/sist/6bd5697e-37fa-42bc-aa4f-f22a959c9a65/iso-dtr-9839>

<u>ILD</u>	<u>Inter-Layer Dielectric</u>
<u>LFM</u>	<u>Latent Fault Metric</u>
<u>ML</u>	<u>Machine Learning</u>
<u>MoL</u>	<u>Middle of Line (sometimes MOL)</u>
<u>MEoL</u>	<u>Middle End of Line (sometimes MEOL)</u>
<u>MPFDTI</u>	<u>Multiple Point Fault Detection Time Interval</u>
<u>NBTI</u>	<u>Negative Bias Temperature Instability</u>
<u>NVM</u>	<u>Non-Volatile Memory</u>
<u>PCM</u>	<u>Phase Change Memory</u>
<u>PHM</u>	<u>Prognostics and Health Management</u>
<u>RUL</u>	<u>Remaining Useful Life</u>
<u>SBD</u>	<u>Soft Breakdown</u>
<u>SHE</u>	<u>Self-Heating Effect</u>
<u>SILC</u>	<u>Stress-Induced Leakage Current</u>
<u>SM</u>	<u>Stress Migration</u>
<u>SoC</u>	<u>System on Chip</u>
<u>SPFM</u>	<u>Single Point Fault Metric</u>
<u>TDDB</u>	<u>Time Dependent Dielectric Breakdown</u>
<u>TDJD</u>	<u>Time Dependent Junction Degradation</u>
<u>TID</u>	<u>Total Ionizing Dose</u>

## 6.5 Literature survey of degrading faults

### 5.1 General

This ~~technical report~~document reviews many technical documents to summarize the current state of the art understanding of degrading faults in industry standards and technical publications.

NOTE  $\div$  Terminology in the referenced publications and standards is not always aligned to ISO 26262 terms and definitions of the ISO 26262 series. When referencing publications and standards, the terminology of the referenced work is used.

### 6.15.2 Degrading faults in industry standards

#### 6.1.15.2.1 JEDEC JEP122H<sup>[4]</sup>

The JEDEC Solid State Technology Association is a semiconductor industry trade association and standardization body. JEDEC has over 300 companies as members and publishes electronics standards on a wide variety of topics.

The JEDEC JEP122H ~~standard~~ is the latest revision on JEDEC's standard for "Failure Mechanisms and Models for Semiconductor Devices," last updated in 2016. The standard describes eighteen different failure mechanisms, classifying them as being related to the die ~~Front End~~front end of Line (FEoL), die ~~Back End~~back end of Line (BEoL), or packaging. Models are provided for estimating the rates of degradation per failure mode. The information provided in JEP122H is validated by a team of reliability experts from the SEMATECH/ISMI Reliability Council and supported by extensive references to technical publications.